



Koh Young Invites You to the 2025 IEEE Electronic Components and Technology Conference, Opening May 27 in Dallas, Texas

Atlanta, GA – Koh Young, the industry leader in True3D™ measurement-based inspection solutions, invites you to join us at the 2025 IEEE Electronic Components and Technology Conference (ECTC), taking place May 27–30, 2025, at the Gaylord Texan Resort & Convention Center in Grapevine, Texas. Now in its 75th year, ECTC is the premier international event dedicated to microelectronic packaging, components, and systems, bringing together global experts for collaboration, education, and innovation.

As the exclusive sponsor of the ECTC Gala, Koh Young is proud to continue its commitment to the advanced packaging community. The 2025 technical program features groundbreaking work in assembly and manufacturing technologies, heterogeneous integration, wafer-level packaging, and semiconductor inspection. Attendees will gain insights from industry leaders through technical sessions, panels, plenaries, and EPS seminars, as well as in the exhibition area.

The ECTC Exhibition offers a vital opportunity for engineers, technologists, and decision makers to engage directly with Koh Young and other technology leaders. Visit booth 419 to learn how our AI-powered 3D inspection solutions are solving critical challenges in advanced packaging and semiconductor applications. Our experts will be on hand to discuss how True 3D measurement and automated process control are helping manufacturers improve quality, reduce waste, and achieve zero-defect production goals.



“As advanced packaging and semiconductor technologies continue to push the limits of precision and reliability, manufacturers need inspection solutions that can keep pace,” said Brent Fischthal, Head of Global Marketing at Koh Young. “At ECTC 2025, we’re excited to connect with engineers and decision makers to explore how our AI-powered 3D metrology solutions enable smarter process control and higher yield. We’re also pleased to introduce our new sales partner, NTV USA, who will help us expand support for customers in these critical application areas.”

To register, visit www.ectc.net/registration. If you are unable to attend in person, explore our inspection innovations anytime at www.kohyoungamerica.com.

###

About Koh Young Technology, Inc.

Founded in 2002, Koh Young pioneered the industry’s first 3D Solder Paste Inspection (SPI) system using patented dual projection Moiré technology. Today, it leads the market in 3D SPI and Automated Optical Inspection (AOI) solutions, with over 24,000 systems installed worldwide at 3,700 global customers and growing. Koh Young’s True 3D technology addresses challenges in electronics manufacturing including surface mount, through-hole, pin insertion, conformal coating, machined parts, semiconductor wafers, and advanced packaging. Guided by user-focused R&D, the company continues to innovate and address evolving market needs. With headquarters in Korea and regional offices worldwide, Koh Young remains close to its customers, delivering trusted solutions for smart manufacturing. Visit www.kohyoungamerica.com or www.kohyoung.com to learn more.



For More Information

Koh Young • 1950 Evergreen Boulevard, Suite 200, Duluth, Georgia 30096 United States • +1.470.374.9254
Brent A Fischthal, Head of Global Marketing • kohyoungamerica.com • america@kohyoung.com